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### (54) WAFER SEPARATION APPARATUS AND METHOD, AND METHOD FOR MANUFACTURING SILICON WAFER

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#### (57)ABSTRACT

It would be helpful to provide a wafer separation apparatus and method, and a method for manufacturing a silicon wafer in which poor wafer separation can be easily prevented. A wafer separation apparatus 1 includes an injection port 2 configured to inject a fluid, a rolling element 3, and a holder 4 configured to movably hold the rolling element 3 in a rollable and integral manner, to be reciprocatable and biased to one side in a reciprocating direction, and to be integrally connected to the injection port 2.

